

描述 / Descriptions

SOT-23塑封封装 肖特基二极管。Schottky barrier diodes in a SOT-23 Plastic Package.

特征 / Features

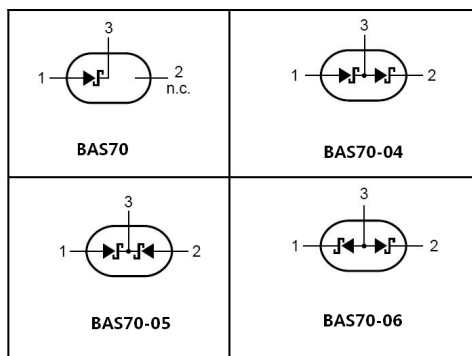
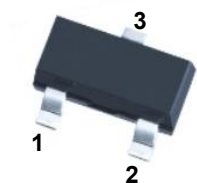
正向开启电流小、反向击穿电压高、小型片式封装。

Low forward current, high breakdown voltage, small plastic SMD package.

用途 / Applications

用于超高速开关、电压钳位、保护电路。

Ultra high-speed switching, voltage clamping, protection circuits.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN: See Equivalent Circuit.

放大及印章代码 / h_{FE} Classifications & Marking

Type	BAS70	BAS70-04	BAS70-05	BAS70-06
Marking	H73	H74	H75	H76


极限参数 / Absolute Maximum Ratings(Ta=25°C)

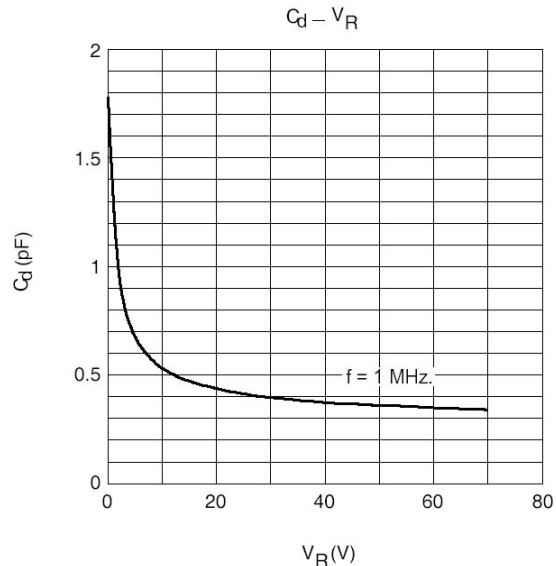
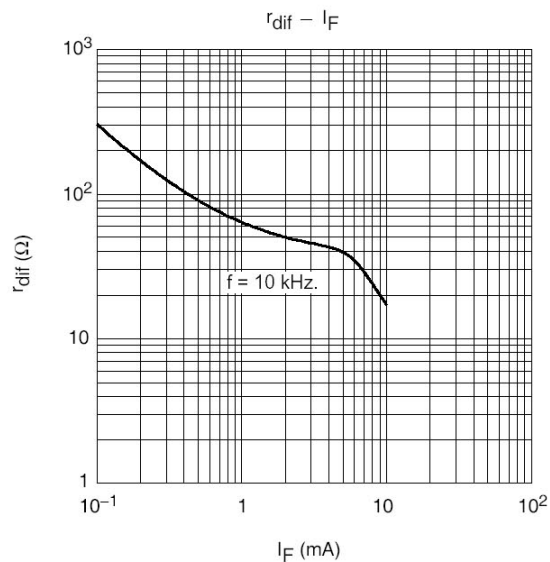
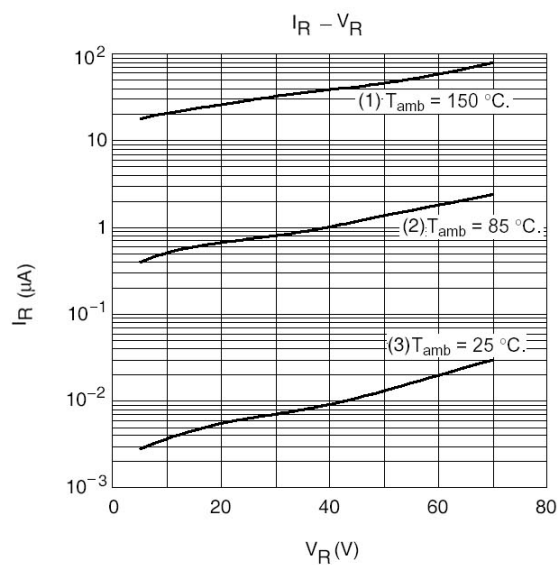
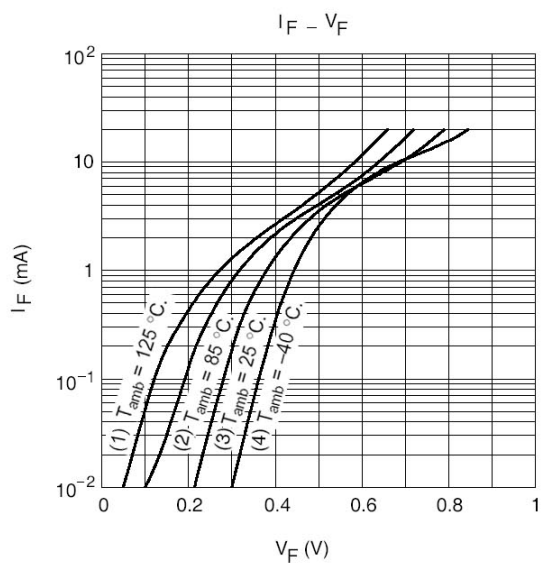
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Repetitive Reverse Voltage	V_R	70	V
Average Rectified Forward Current	I_F	70	mA
Repetitive Peak Forward Surge Current	I_{FRM}	70	mA
Non-repetitive Peak Forward Surge Current	I_{FSM}	100	mA
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Forward Voltage	V_F	$I_F=1mA$			410	mV
		$I_F=10mA$			750	mV
		$I_F=15mA$			1	V
Instantaneous Reverse Current	I_R	$V_R=50V$			0.1	μA
		$V_R=70V$			10	μA
Total Capacitance	C_T	$V_R=0$ $f=1MHz$			2	pF



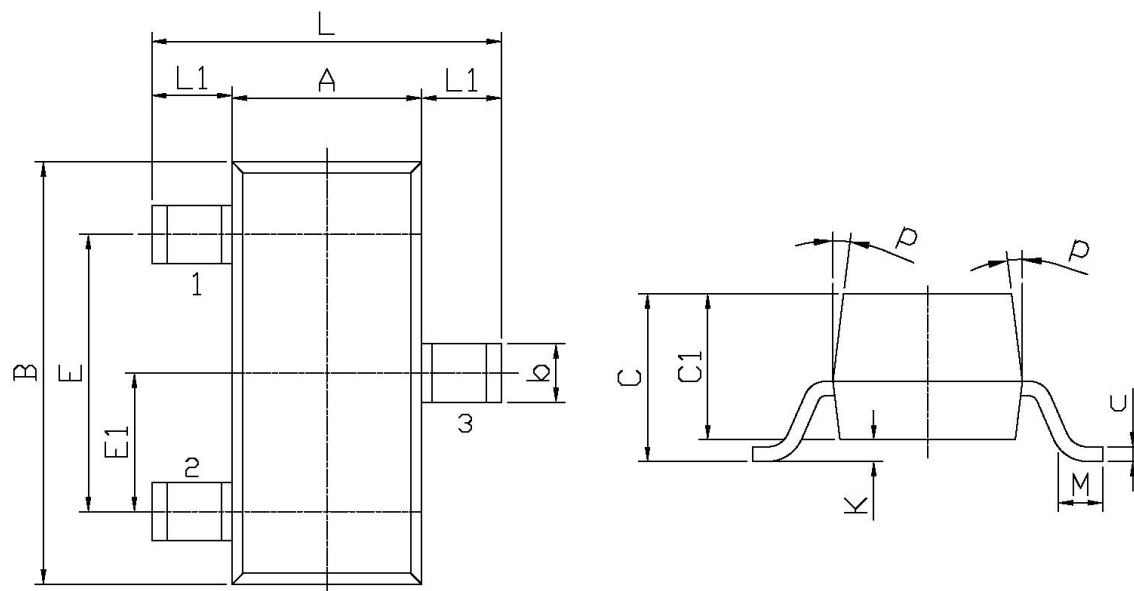
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

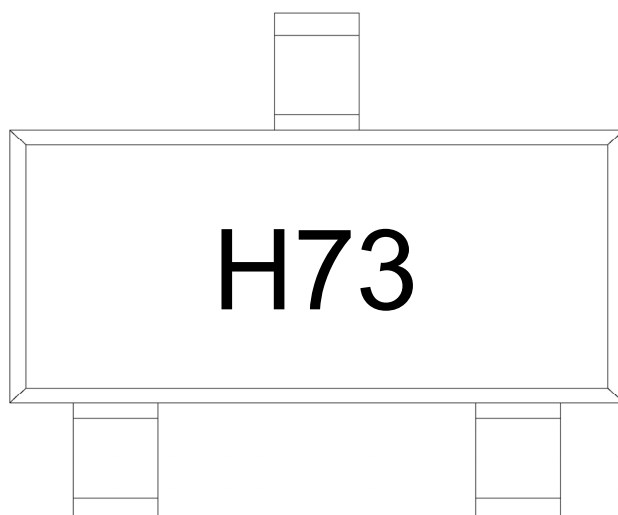
SOT-23

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
B	2.70	3.10	K	0	0.10
E	1.70	2.10	M	0.20MIN	
E1	0.85	1.05	P	7°	
b	0.35	0.55			

印章说明 / Marking Instructions



说明：

H： 为公司代码

73： 为型号代码

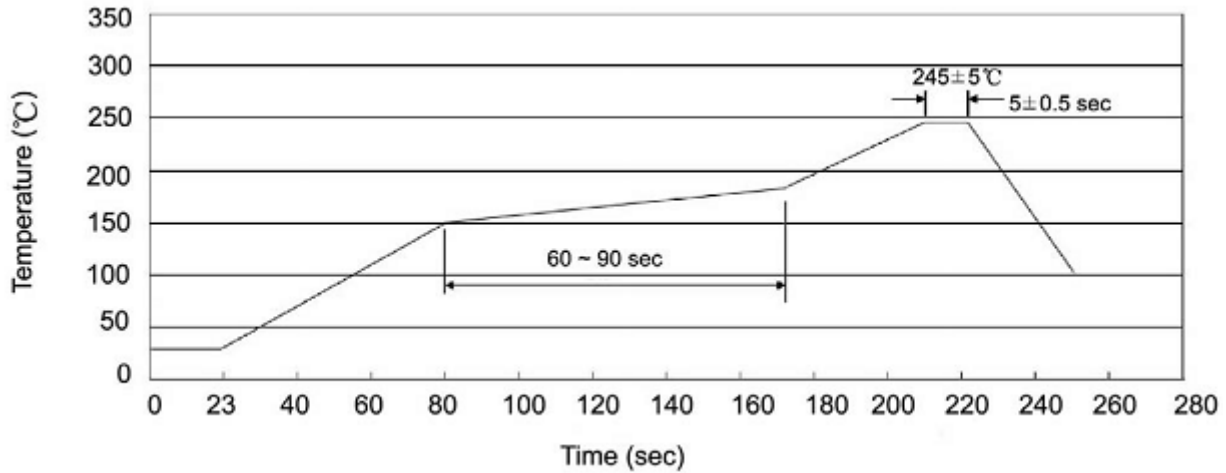
Note:

H: Company Code.

73: Product Type.



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	8	240,000	7" x8	180×120×180	385×257×392

使用说明 / Notices